



Initial Product/Process Change Notification

Document #: IPCN26627X

Issue Date: 22 Jul 2026

Title of Change:	Manufacturing Site Transfer and 12-inch Wafer Addition for T6 60V D2F Process in East Fishkill, USA
Proposed First Ship date:	29 Jan 2027 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	the change material can be identified by lot code or date code
Change Category:	Addition of 12-inch wafers, Test Change, Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Transfer, Material Change

Sites Affected:

onsemi Sites

onsemi, East Fishkill

External Foundry/Subcon Sites

None

Description and Purpose:

onsemi wishes to inform customers of the qualification of the onsemi East Fishkill, USA facility as a wafer fabrication site transfer for T6 Technology.

This change is to enhance manufacturing capacity and flexibility.

	Before Change Description	After Change Description	
FAB Site	Aizu in Japan	Aizu in Japan	onsemi, East Fishkill (EFK)
Backgrind Site	Seremban Wafer Fab in Malaysia or Bucheon (KRH)	Seremban Wafer Fab in Malaysia or Bucheon (KRH)	onsemi, East Fishkill (EFK)
Probe Site	Seremban Wafer Fab in Malaysia or Bucheon (KRH)	Seremban Wafer Fab in Malaysia or Bucheon (KRH)	onsemi, East Fishkill (EFK)
Wafer size	8 inch	8 inch	12 inch
OPN nomenclature	POR	POR	Identifier "E" added
Mold Compound	G700LS Sumitomo Bakelite	G700LAE Sumitomo Bakelite	

There is no product marking change because of this change



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Qualification Plan:

QV DEVICE NAME : NVMF55C604NT1G

RMS : 105929 and 105932

PACKAGE : SO8FL

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta= _175_ °C, _100_ % max rated V	_1008_ hrs
High Temperature Gate Bias	JESD22-A108	Ta= _175_ °C, 100% max rated Vgss	_1008_ hrs
High Temperature Storage Life	JESD22-A103	Ta= _175_ °C	_1008_ hrs
Preconditioning	J-STD-020 JESD-A113	MSL _1_ @ _260_ °C	
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = _2_ min	_15000_ cyc
Temperature Cycling	JESD22-A104	Ta= - _55_ °C to + _150_ °C	_1000_ cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	_96_ hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	_96_ hrs

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NTMFSCHT1D5N06CTWG	#NONE	NVMF55C604NT1G
NTMF55C612NT1G	#NONE	NVMF55C604NT1G
NTMFSC1D6N06CTWG	#NONE	NVMF55C604NT1G